

Connector for RS-MMC™

SCDC Series

Two compact, low-profile types are available to support a broad range of personal digital assistants and mobile phones.

For SD Memory Card

For miniSD™ Card

For microSD™ Card

For RS-MMC™

For W-SIM™

For Memory Stick Micro™

For Memory Stick™

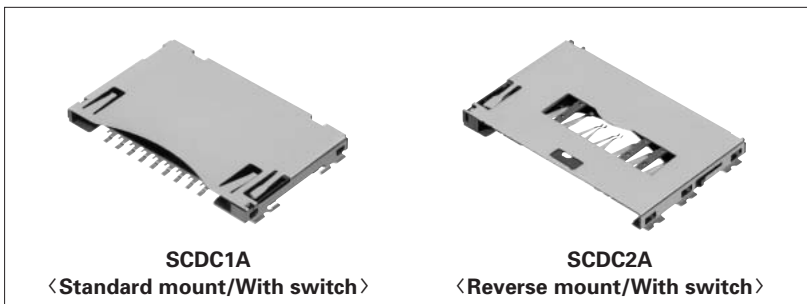
Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module



RoHS applicable

Features

- Compact, low-profile design fits the use with portable devices.
- Available for reflow soldering.

Applications

- Various portable devices such as mobile phones and personal digital assistants

Typical Specifications

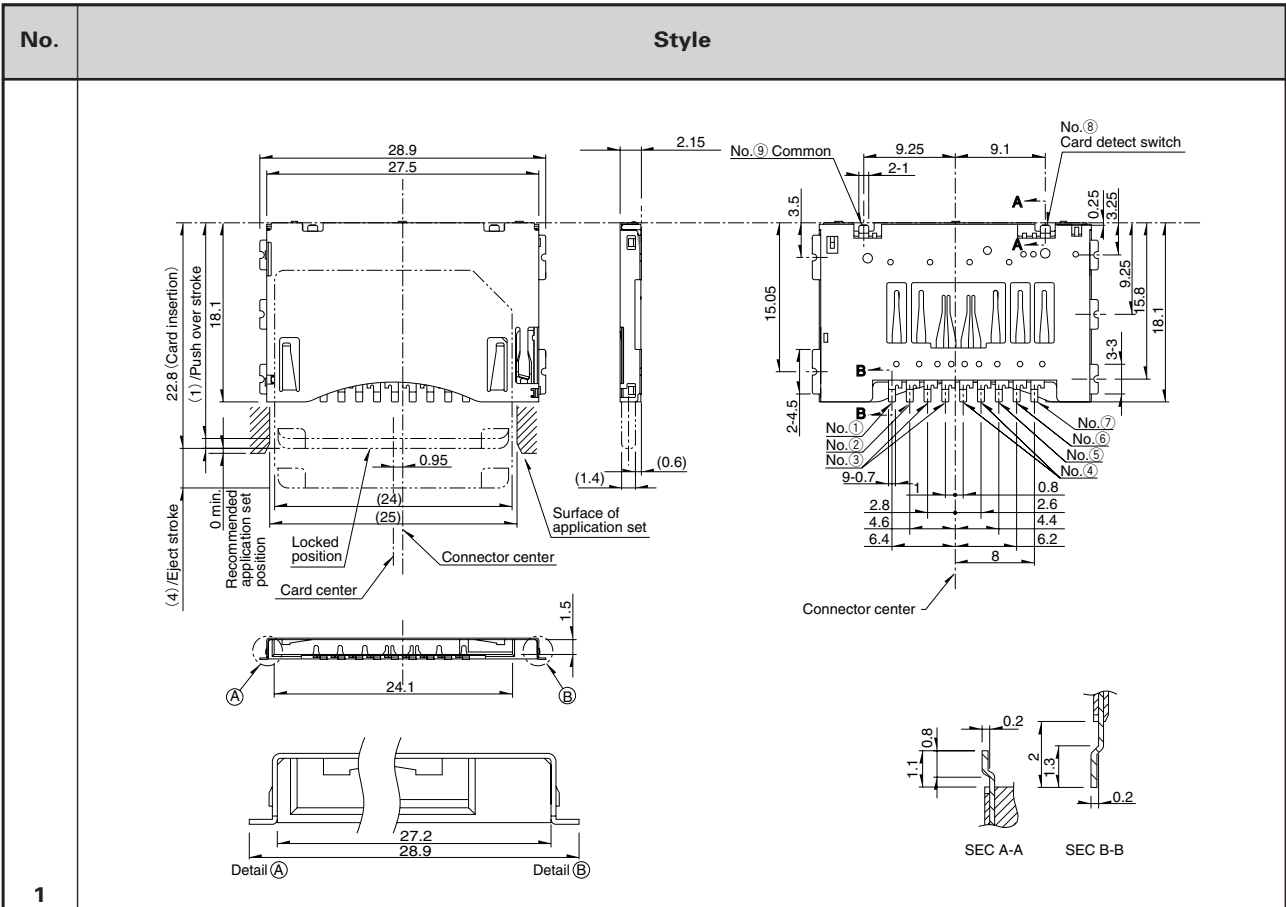
Items		Specifications		
		SCDC1A	SCDC2A	
Structure	Dimension	28.9×18.1×2.15mm	28.9×18.4×2.4mm	
	Media detection switch	With switch		
	Mounting system	Standard mount	Reverse mount	
	Applicable card	RS-MMC™		
	Mounting method	Surface mounting type		
	Media ejection structure	Push-push type		
Performance	Operating temperature range	-25°C to +60°C		
	Voltage proof	500V AC 1 minute		
	Insulation resistance (Initial)	1,000MΩ min.		
	Contact resistance (Initial)	Connector contacts	100mΩ max.	
		Detection switch	500mΩ max.	
Mating and unmating cycle	10,000 cycles			

Products List

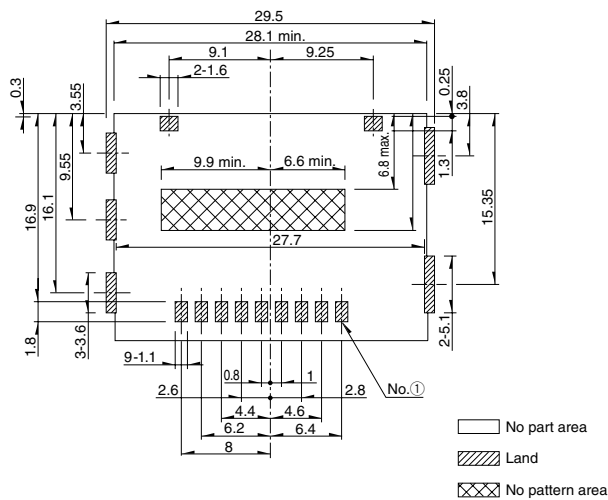
Media ejection structure	Mounting system	Features	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	With switch	0	Taping	SCDC1A0102	1
	Reverse mount				SCDC2A0102	2

Dimensions
Standard mount

Unit:mm



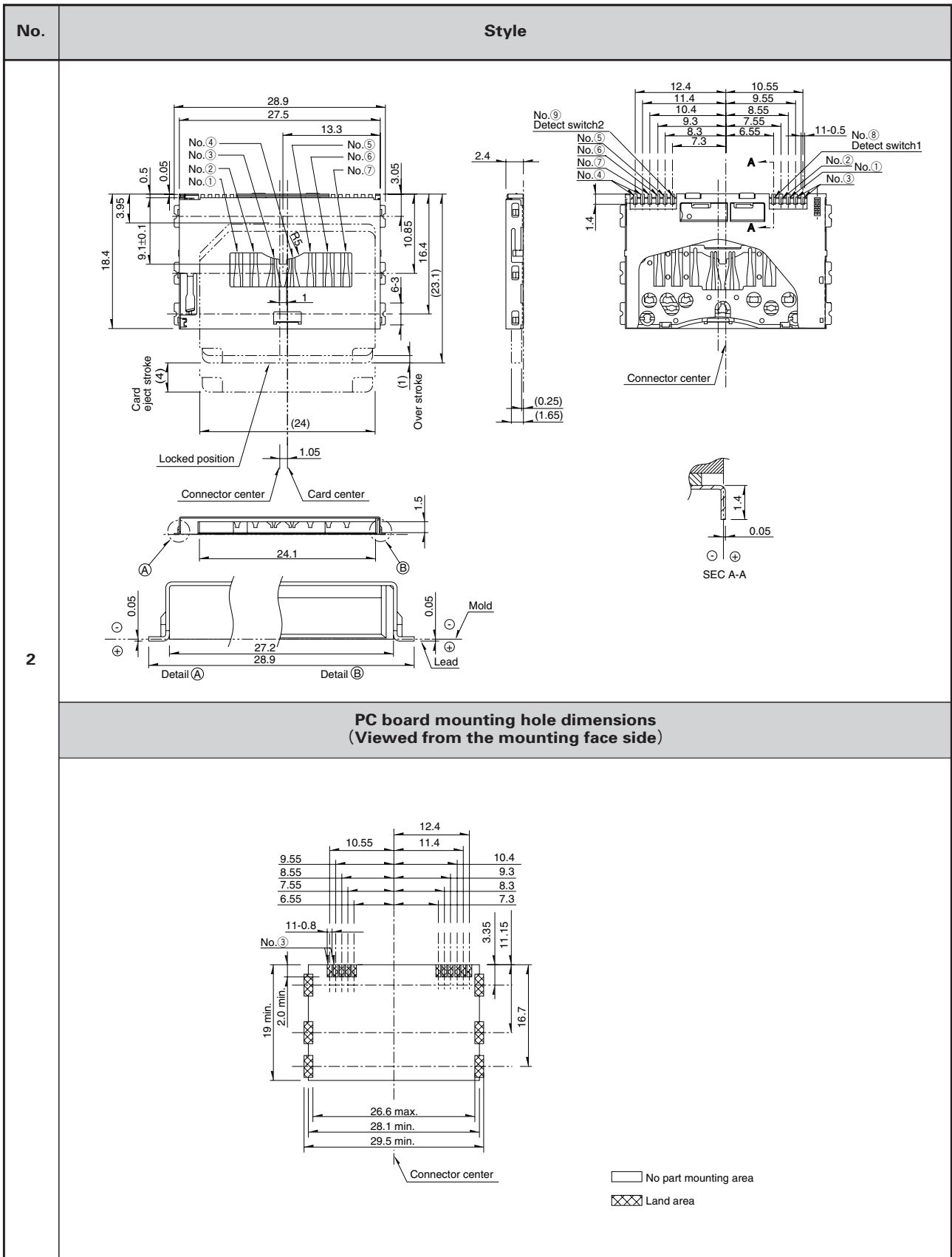
**PC board mounting hole dimensions
(Viewed from the mounting face side)**



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Dimensions
Reverse mount

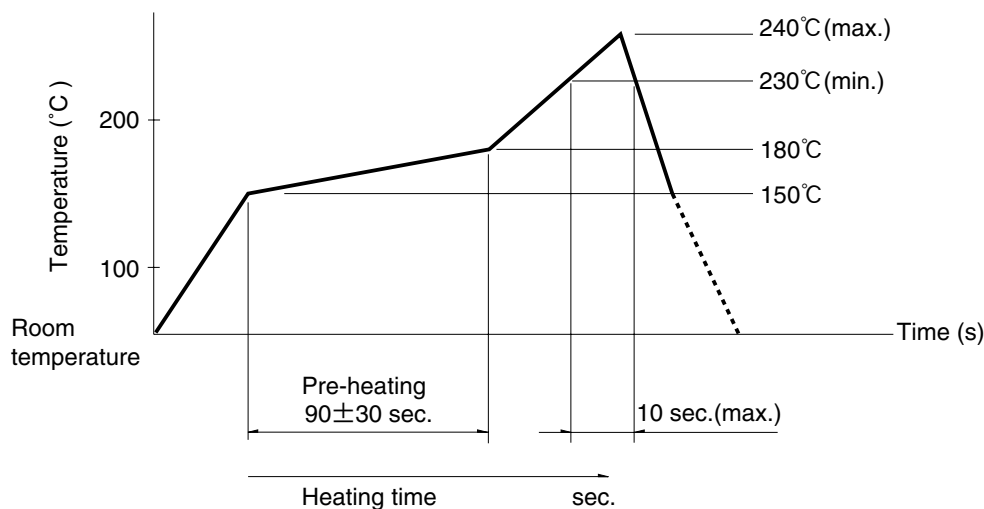
Unit:mm



Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. When soldering, do not use water soluble flux because this may corrode the product.
3. Regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.
4. As PC board warping may alter characteristics, please take this into consideration when designing pattern and layout.
5. This product has been designed and manufactured for applications to ordinary electronic equipment and devices such as the AV equipment, electric home applications, office machines and communications equipment, consequently, when employing these products for applications requiring a high degree of safety and reliability such as the medical equipment, aviation and aircraft equipment, space equipment and burglar alarm equipment, the using manufacturers will please thoroughly study the proprieties of these products for the planned applications.
6. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

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